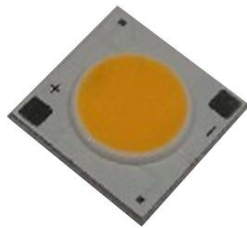


CUSTOMER : _____.

DATE : 2012. 04. 03.

SPECIFICATIONS FOR APPROVAL



4W MCP (Warm White/ 2,700K)

MODEL NAME : LEMWM11202MZ00

APPROVAL	REMARK	APPENDIX

Designed	Checked	Approved

SPECIFICATION

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Change History of Revision

[illegible]

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SPECIFICATION

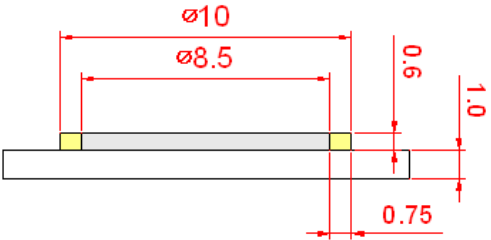
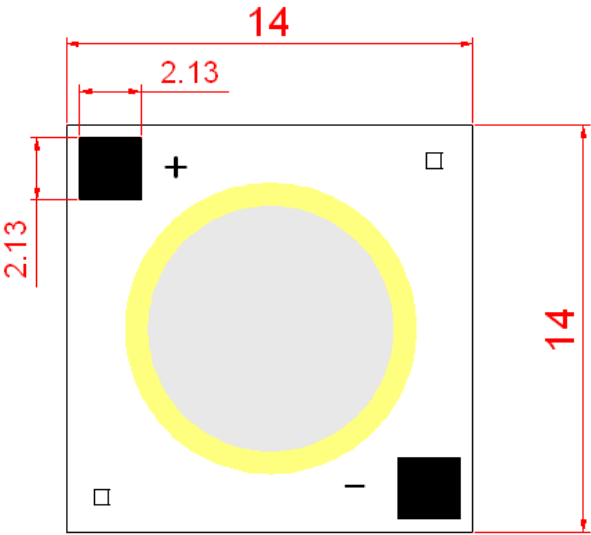
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1. Features

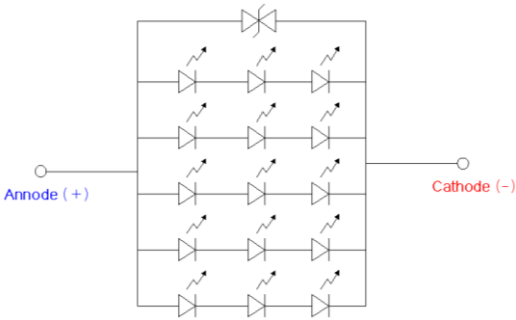
- High flux power LED COB module
- Compact design (14mmX14mm)
- 110° light distribution pattern, uniform illumination
- Low thermal resistance Rth,j-board < 4 K/W (25℃)

2. Outline Dimensions

(unit : mm)



Circuit Diagram



◆Tolerances Unless Dimension $\pm 0.2\text{mm}$

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3. Applications

- Indoor Lighting (Bulb, Down light, Spot light)

4. Characteristics

(Ta=25℃)

Items	Symbol	Min	Typ	Max	Unit
All data for Ta=25℃, IF=400mA					
Power *1)	Po	3.6	3.8	4.0	W
Forward Voltage *1)	VF	9.0	9.5	10.0	V
Luminance Flux *1)	Φ_v	350	380	-	lm
Luminous Efficacy	lm/W	90	100	-	lm/W
Color Temperature *1)	CCT	2,580	2,725	2,870	K
Color Rendering Index *1)	Ra	80	83	-	-
Viewing Angle *1)	2 Θ 1/2	-	115	-	deg
Junction Temperature *2)	Tj	-	-	120	℃
Thermal Resistance *2)	Rth j-b	-	3.8	-	℃/W

※ These values measured by Optical Spectrum Analyzer of LG Innotek Co., LTD

Tolerances are followings as below

- Luminous Flux (lm) : $\pm 20\%$, CIE Value : ± 0.01 , CRI : ± 2

※ Rthj-b = Thermal Resistance (Junction – Board)

If the maximum temperature limits are exceeded, the life of the module will be greatly reduced or the module may be damaged

*1) These values measured without heat sink

*2) These values is allowed to measure with a heat sink of aluminum

5. Absolute Maximum Ratings

(Ta=25℃)

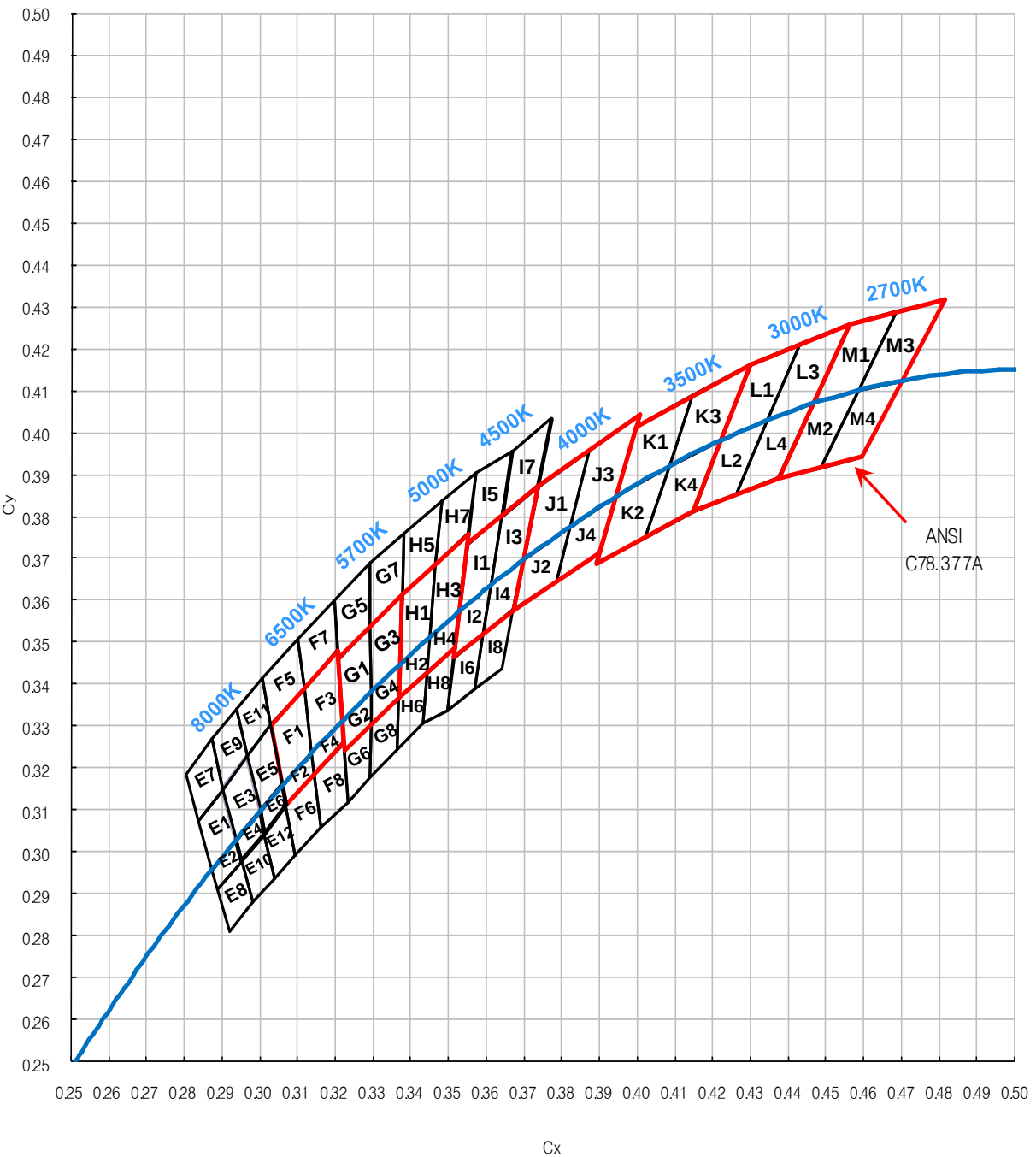
Items	Symbol	Rating	Unit
Forward Current	IF	750	mA
Pulse Forward Current *1)	IFP	1,000	mA
Power Consumption	PD	7.8	W
Operating Temperature	Topr	-30 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +100	℃

*1) Pulse Width $\leq 10\text{msec}$, Duty $\leq 10\%$

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6. Chromaticity on the 1931 CIE Curve



- Chromaticity coordinate groups are tested at a current pulse duration of 300 ms and a tolerance of ± 0.01 .
- ANSI Cool/Neutral/Warm white

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7. Performance Group - Chromaticity

Rank of CIE Value (@400mA)

CCT	Rank	CIE X	CIE Y	CCT	Rank	CIE X	CIE Y	CCT	Rank	CIE X	CIE Y
2700K (2725K ±145K)	M1	0.4562	0.4260	4500K (4503K ±243K)	I1	0.3548	0.3736	5700K (5665K ±355K)	G1	0.3207	0.3462
		0.4687	0.4289			0.3641	0.3804			0.3291	0.3538
		0.4586	0.4103			0.3611	0.3638			0.3292	0.3382
		0.4465	0.4071			0.3526	0.3575			0.3217	0.3314
	M2	0.4465	0.4071		I2	0.3526	0.3575		G2	0.3217	0.3314
		0.4586	0.4103			0.3611	0.3638			0.3292	0.3382
		0.4483	0.3918			0.3590	0.3521			0.3293	0.3305
		0.4373	0.3893			0.3512	0.3465			0.3222	0.3243
	M3	0.4687	0.4289		I3	0.3641	0.3804		G3	0.3291	0.3538
		0.4813	0.4319			0.3736	0.3874			0.3376	0.3616
		0.4700	0.4126			0.3697	0.3697			0.3369	0.3449
		0.4586	0.4103			0.3611	0.3638			0.3292	0.3382
	M4	0.4586	0.4103		I4	0.3611	0.3638		G4	0.3292	0.3382
		0.4700	0.4126			0.3697	0.3697			0.3369	0.3449
		0.4593	0.3944			0.3670	0.3578			0.3366	0.3369
		0.4483	0.3918			0.3590	0.3521			0.3293	0.3305
3000K (3045K ±175K)	L1	0.4299	0.4165		I5	0.3571	0.3907		G5	0.3196	0.3602
		0.4430	0.4212			0.3668	0.3957			0.3290	0.3690
		0.4344	0.4032			0.3641	0.3804			0.3291	0.3538
		0.4221	0.3984			0.3548	0.3736			0.3207	0.3462
	L2	0.4221	0.3984		I6	0.3512	0.3465		G6	0.3222	0.3243
		0.4344	0.4032			0.3590	0.3521			0.3293	0.3305
		0.4260	0.3853			0.3567	0.3389			0.3290	0.3180
		0.4147	0.3814			0.3495	0.3339			0.3231	0.3120
	L3	0.4430	0.4212		I7	0.3668	0.3957		G7	0.3290	0.3690
		0.4562	0.4260			0.3771	0.4034			0.3381	0.3762
		0.4465	0.4071			0.3736	0.3874			0.3376	0.3616
		0.4344	0.4032			0.3641	0.3804			0.3291	0.3538
	L4	0.4344	0.4032		I8	0.3590	0.3521		G8	0.3293	0.3305
		0.4465	0.4071			0.3670	0.3578			0.3366	0.3369
		0.4373	0.3893			0.3640	0.3440			0.3361	0.3245
		0.4260	0.3853			0.3567	0.3389			0.3290	0.3180
3500K (3465K ±245K)	K1	0.3996	0.4015	5000K (5028K ±283K)	H1	0.3376	0.3616	6500K (6530K ±510K)	F1	0.3028	0.3304
		0.4146	0.4089			0.3463	0.3687			0.3115	0.3391
		0.4082	0.3922			0.3447	0.3513			0.3136	0.3237
		0.3941	0.3848			0.3369	0.3449			0.3059	0.3160
	K2	0.3941	0.3848		H2	0.3369	0.3449		F2	0.3059	0.3160
		0.4082	0.3922			0.3447	0.3513			0.3136	0.3237
		0.4017	0.3752			0.3440	0.3427			0.3144	0.3186
		0.3889	0.3690			0.3366	0.3369			0.3068	0.3113
	K3	0.4146	0.4089		H3	0.3463	0.3687		F3	0.3115	0.3391
		0.4299	0.4165			0.3551	0.3760			0.3205	0.3481
		0.4221	0.3984			0.3526	0.3575			0.3217	0.3314
		0.4082	0.3922			0.3447	0.3513			0.3136	0.3237
	K4	0.4082	0.3922		H4	0.3447	0.3513		F4	0.3136	0.3237
		0.4221	0.3984			0.3526	0.3575			0.3217	0.3314
		0.4147	0.3814			0.3515	0.3487			0.3221	0.3261
		0.4017	0.3752			0.3440	0.3427			0.3144	0.3186
4000K (3985K ±275K)	J1	0.3736	0.3874		H5	0.3381	0.3762		F5	0.3005	0.3415
		0.3870	0.3958			0.3480	0.3840			0.3099	0.3509
		0.3819	0.3776			0.3463	0.3687			0.3115	0.3391
		0.3697	0.3697			0.3376	0.3616			0.3028	0.3304
	J2	0.3697	0.3697		H6	0.3366	0.3369		F6	0.3068	0.3113
		0.3819	0.3776			0.3440	0.3427			0.3144	0.3186
		0.3783	0.3646			0.3429	0.3307			0.3161	0.3059
		0.3670	0.3578			0.3361	0.3245			0.3093	0.2993
	J3	0.3870	0.3958		H7	0.3480	0.3840		F7	0.3099	0.3509
		0.4006	0.4044			0.3571	0.3907			0.3196	0.3602
		0.3941	0.3848			0.3551	0.3760			0.3205	0.3481
		0.3819	0.3776			0.3463	0.3687			0.3115	0.3391
	J4	0.3819	0.3776		H8	0.3440	0.3427		F8	0.3144	0.3186
		0.3941	0.3848			0.3515	0.3487			0.3221	0.3261
		0.3898	0.3716			0.3495	0.3339			0.3231	0.3120
		0.3783	0.3646			0.3429	0.3307			0.3161	0.3059

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7. Performance Group – Chromaticity (Continued)

CCT	Rank	CIE X	CIE Y	CCT	Rank	CIE X	CIE Y	CCT	Rank	CIE X	CIE Y
8000K (8020K ±980K)	E1	0.2835	0.3075	8000K (8020K ±980K)	E7	0.2803	0.3185				
		0.2772	0.2992			0.2735	0.3100				
		0.2807	0.2884			0.2772	0.2992				
		0.2870	0.2957			0.2835	0.3075				
	E2	0.2870	0.2957		E8	0.2885	0.2910				
		0.2807	0.2884			0.2824	0.2840				
		0.2824	0.2840			0.2860	0.2740				
		0.2885	0.2910			0.2920	0.2810				
	E3	0.2900	0.3150		E9	0.2870	0.3270				
		0.2835	0.3075			0.2803	0.3185				
		0.2870	0.2957			0.2835	0.3075				
		0.2935	0.3029			0.2900	0.3150				
	E4	0.2935	0.3029		E10	0.2950	0.2980				
		0.2870	0.2957			0.2885	0.2910				
		0.2885	0.2910			0.2920	0.2810				
		0.2950	0.2980			0.2980	0.2880				
	E5	0.2965	0.3230		E11	0.2938	0.3343				
		0.2900	0.3150			0.2870	0.3270				
		0.2935	0.3029			0.2900	0.3150				
		0.3000	0.3100			0.2965	0.3230				
	E6	0.3000	0.3100		E12	0.3010	0.3045				
		0.2935	0.3029			0.2950	0.2980				
		0.2950	0.2980			0.2980	0.2880				
		0.3010	0.3045			0.3037	0.2937				

※ Model name method: Please refer to the following
example Model Name : LEMWM112 02 MZ00

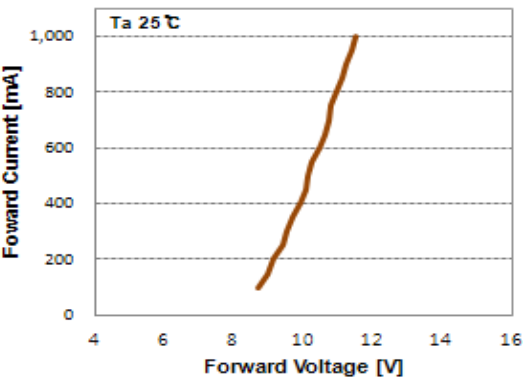


SPECIFICATION

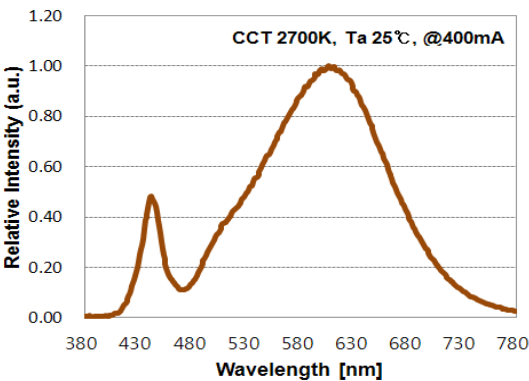
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8. Typical Characteristic Curves

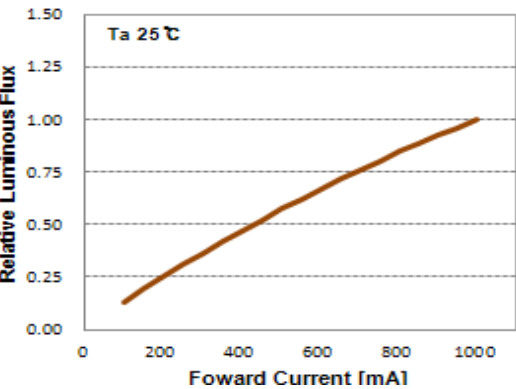
■ Forward Voltage vs. Forward Current



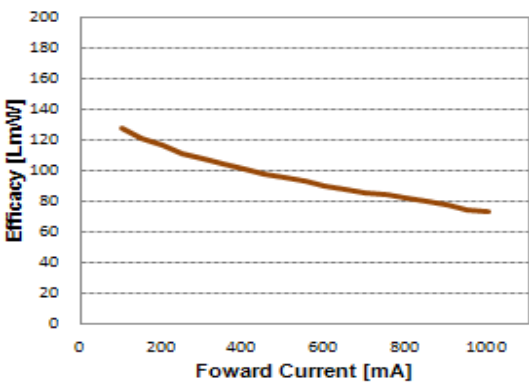
■ Spectrum



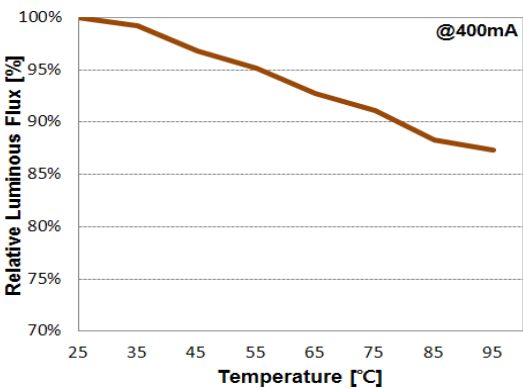
■ Forward Current vs. Luminous Flux



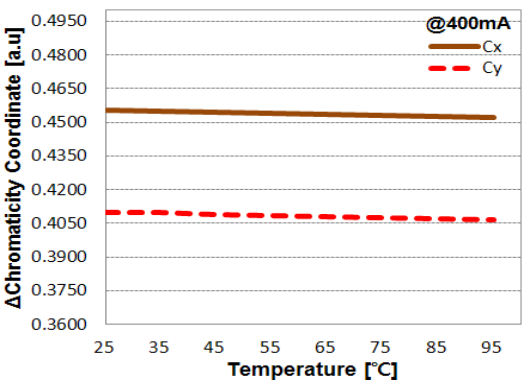
■ Input Watt vs. Luminance Flux



■ Luminous Flux vs. Temp.



■ CIE vs. Temp.

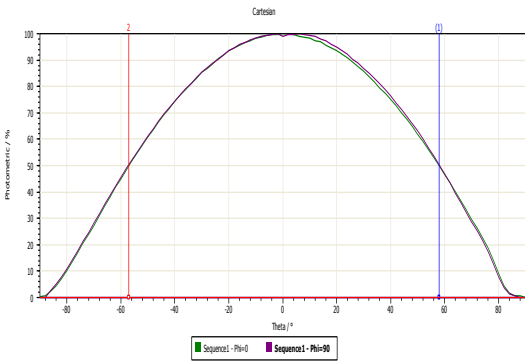
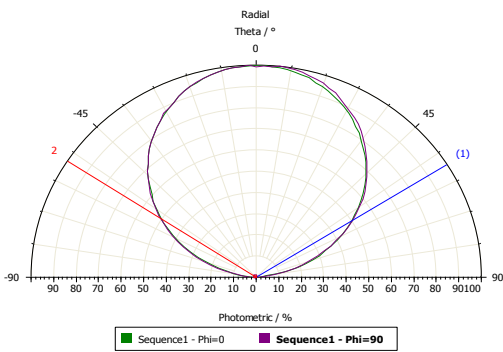


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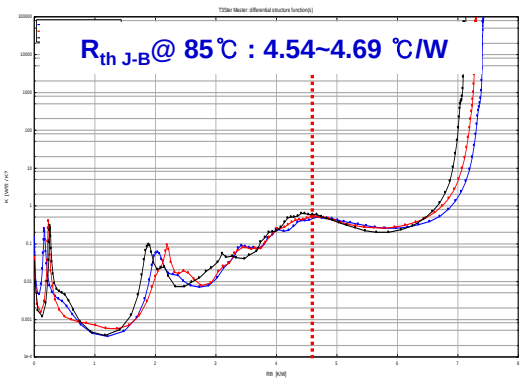
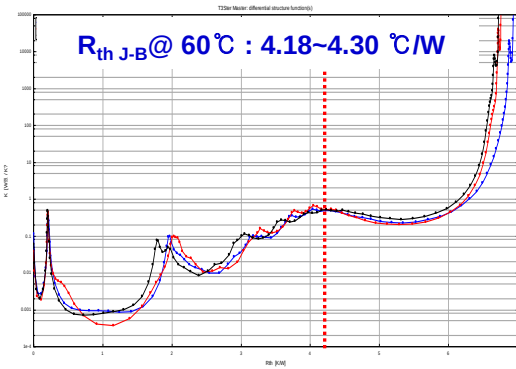
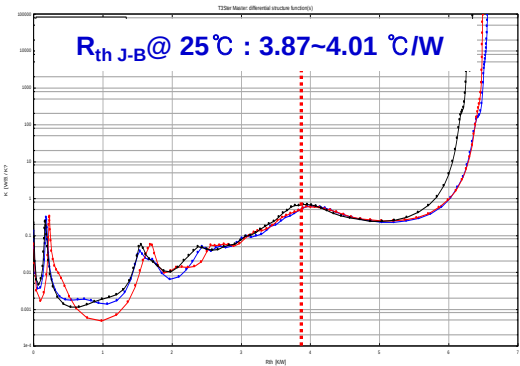
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8. Typical Characteristic Curves (Continued)

■ Viewing Angle



■ Thermal Resistance (junction~Board)



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9. Reliability Test Items and Conditions

9-1.Criteria for Judging the Damage

Item	Symbol	Test Condition	Limit	
			Min	Max
Forward Voltage	VF	IF = 400mA	S × 0.80	S × 1.20
Luminous Flux I ^{*1}	Φ _V	IF = 400mA	S × 0.85	-
Luminous Flux II ^{*2}	Φ _V	IF = 400mA	S × 0.70	-

* U.S.L : Upper Spec. Limit, S : Initial Value

9-2. Item and Results of Reliability Test

No	Item	Test Condition	Test Hours/ Cycles	Sample No	Ac/Re
1	Steady State Operating Life ^{*1}	Ta=25℃, I _F =400 [mA]	1000hr	22 pcs	0 / 1
2	High Temp. Humidity Life	Ta=60℃, 90% RH, I _F =400 [mA]	1000hr	22 pcs	0 / 1
3	Steady State Operating Life of High Temperature ^{*1}	Ta=60℃, I _F =400 [mA]	1000hr	22 pcs	0 / 1
4	Steady State Operating Life of High Temperature ^{*2}	Ta=85℃, I _F =400 [mA]	1000hr	22 pcs	0 / 1
5	Steady State Operating Life of Low Temperature ^{*2}	Ta= -30℃, I _F =400 [mA]	1000hr	22 pcs	0 / 1
6	High Temp. Storage	100℃	1000hr	22 pcs	0 / 1
7	Low Temp. Storage	-40℃	1000hr	22 pcs	0 / 1
8	Temperature Cycle	-40℃ (30min) ~ 25℃ (5min) ~ 100℃ (30min) ~ 25℃ (5min)	100cycle	22 pcs	0 / 1
9	Thermal Shock	100℃ (30min) ~ -40℃ (30min)	100cycle	22 pcs	0 / 1
10	Resistance to Soldering Heat (Reflow Soldering)	Tsld = 260℃, 10s (pre treat. 30℃, 70%, 168hr)	1 times	22 pcs	0 / 1
11	Vibration	200m/s ² , 100~2000Hz(sweep 4min) 48min, 3 directions	4 times	22 pcs	0 / 1
12	Electrostatic Discharge	R=1.5kΩ, C=100pF, Test Voltage 5kV	3times Negative/ Positive	22 pcs	0 / 1

*The operating test is allowed with a heat sink of aluminum

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10. Package and Marking of Products

(unit : mm)

10-1. Tube Outline Dimension

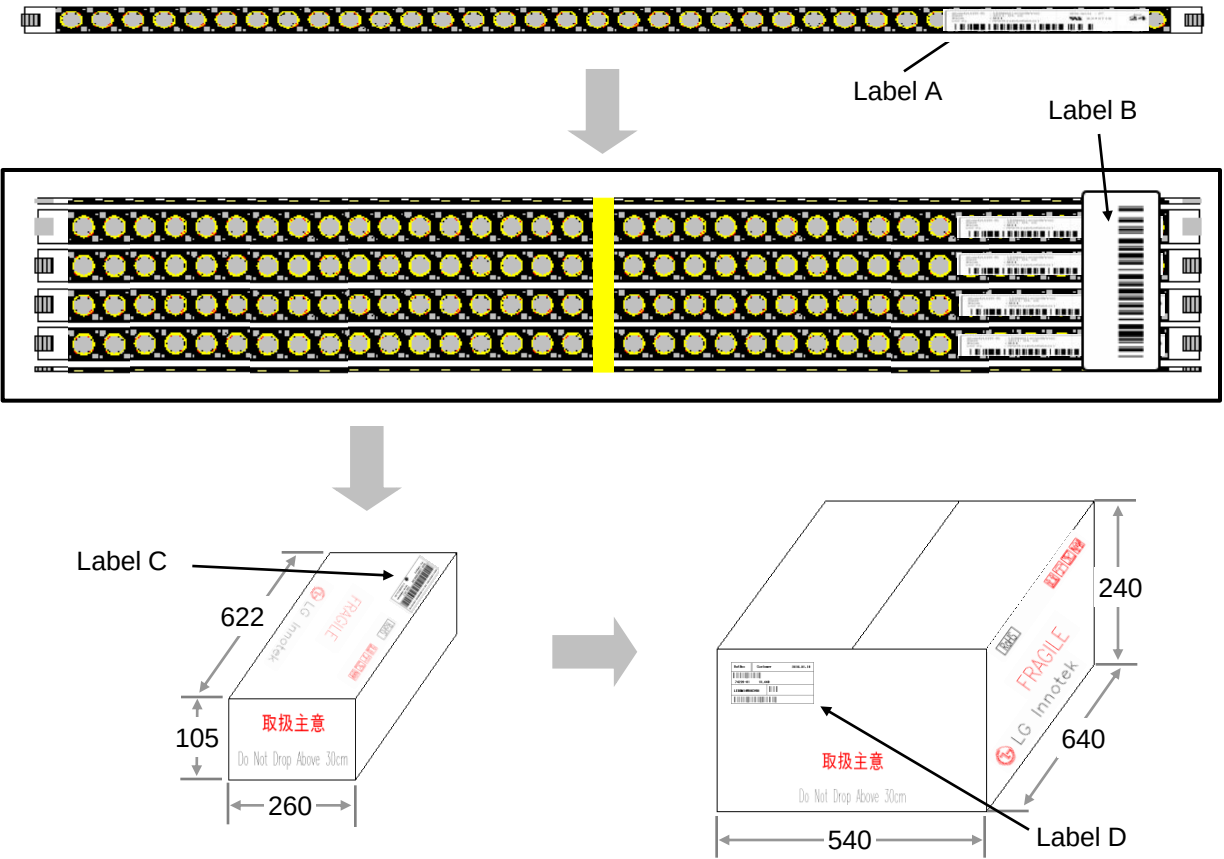
◆ Packing Materials :
- Tube : PET



- ✓ Dimension of Tube : 540 x 16 x 5.5
- ✓ Insert Direction : 36units Per Tube

10-2. Packing Specifications

A rubber band ties the 10 Tubes (the number of PKGs are 360 pcs) and then that packed in a vacuum seal off Packing Bag along with desiccants (Silicagel). 10 Packing Bag (total maximum number of products are 3,600 pcs) packed in an inner box and 4 inner boxes are put into an outer box. (total maximum number of products are 14,400 pcs)



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※. Label A (Tube Label)

Model(Company's Name - Location of manufacture) , Date, Rank, LOT ID, Quantity

Model (LGIT – P) : M11202M

Date : 2011 – 12 – 13

Rank : 2-M3

LOT ID : PPLE20M1CDT000198



Q'ty (pcs) : 36

BIN

003

90mm

13mm

※ Label B (Packing Bag)

PACK ID, MODEL, RANK, Quantity, RUN No, Rack No

PACK ID : MP11C16140102



MODEL : M11202M

RANK : 2-M3

M11202M =2-M3=360=P11C16-00054=M-001



Rack No: M - 001

Q'ty:360[pcs]

RUN No : P11C16 – 0005

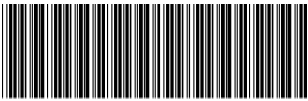
80mm

40mm

※ Label C (Inner Box Label)

INNER BOX ID, MODEL, Quantity, Date, Rank

INNER BOX ID : PSI1C16304



Model : LEMWM11202MZ00

Q'ty : 3,600

Date : 2011.12.16

Rank : 2-M3

80mm

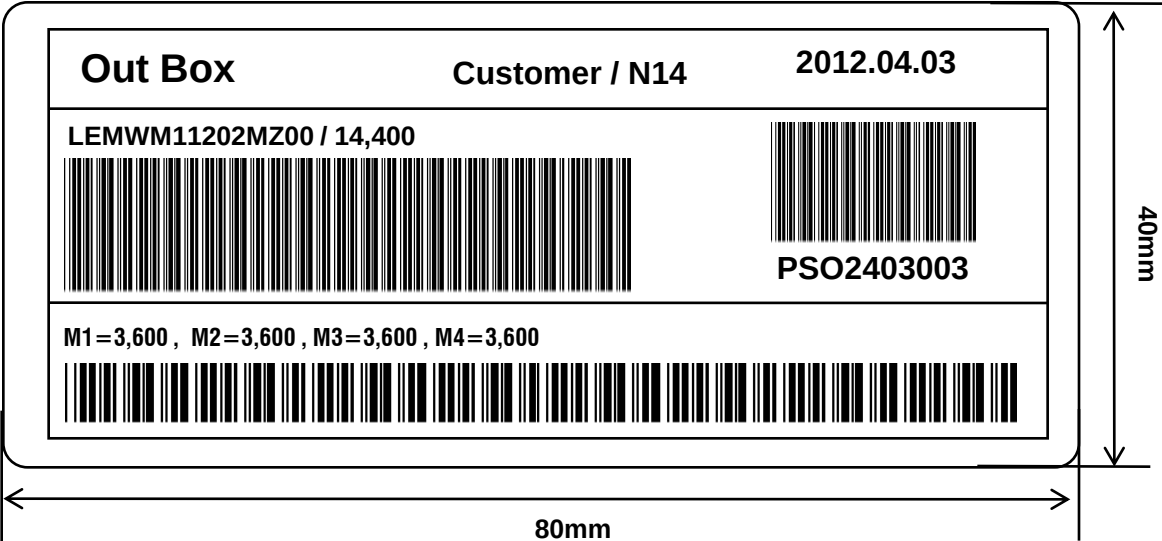
40mm

SPECIFICATION

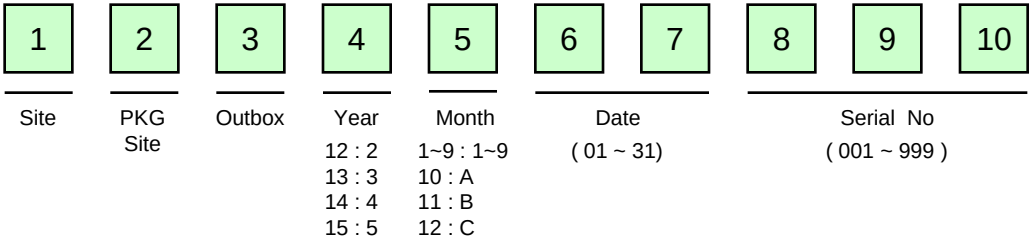
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※ Label D (Out Box Label)

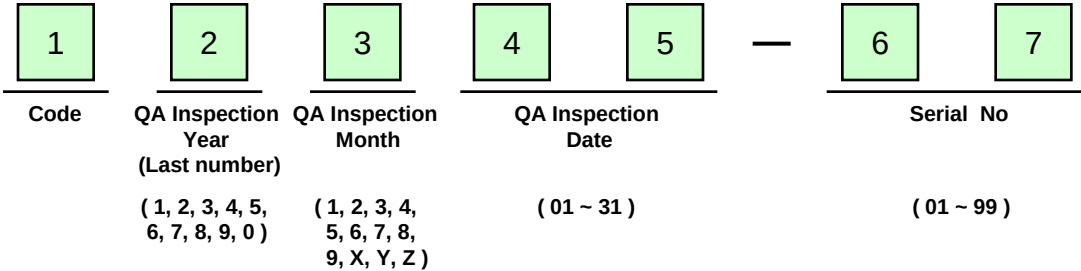
Specifying Customer, Date, Model Name, Quantity, Customer Part no, Outbox ID



■ Outbox ID. indication



■ Lot No. indication



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11. Cautions on use

11-1. Over-current-proof

Customer must apply resistors for protection, others slight voltage shift will cause big current change. (Burn out will happen)

LG Innotek will not be held responsible for any damage to the user that may result from accidents or any other reasons during operation of the user's unit if use to exceed the absolute maximum ratings, or not keep the matters that demand special attention.

11-2. For the Storage

- Proper temperature and RH conditions for storage are : 5 °C ~35 °C , RH 60%.
- Do not open moisture-proof bag before the products are ready to use.
- Store products in a moisture-proof bag with a desiccant (Silica gel) after open.
- These products should be used within 168 hours after opening the bag based upon storage condition.
- These products must be baked to remove moisture before using them if the Silica gel loses its color. Conditions for baking are 60±5°C , 20% (RH) and 24 hours maximum. (For reeled status without bag)

11-3. For the Usage

- LED PKG should not be used in directly exposed environment containing hazardous substances.
- The LEDs has silver plated metal parts. The silver plating become tarnished when being exposed to an environment which contains corrosive gases.
- After assembly and during use, silver plating can be affected by the corrosive gases emitted by components and materials in close proximity of the LEDs within an end product, and the gases entering into the product from the external atmosphere.
- Do not expose the LEDs to corrosive atmosphere during storage and using.
- Avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.
- In designed a circuit, the current through each LED must not exceed the absolute maximum rating.

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11. Cautions on use (Continued)

11-4. Cleaning

- Please avoid using a brush for cleaning and do not wash the product in organic solvents such as acetone, Organic solvent (TCE, etc..) will damage the surface of LED. Please refer to following olvents and conditions.

Solvent : alcohol, 25℃ max × 600sec max

11-5. Handling

- Do not exceed 2kgf on top-Lens. (Do not exceed 1kgf side Lens)
- Do not drop above 30cm.

11-6. Heat Generation

- Thermal design of the end product is of paramount importance.
- Please consider the heat generation of the LED when making the system design.
- The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board. as well as other component.
- It necessary to avoid intense heat generation and operate within the maximum ratings given in the specification.

11-7. Static Electricity

- If over-voltage, which exceeds the absolute maximum rating, is applied to the LEDs, it will damage the LEDs and result in destruction. Since the LEDs are sensitive to the static electricity and surge, it is strongly recommended to use a wristband or anti-electrostatic glove when handling the LEDs and all devices, equipment and machinery must be properly grounded.
- It is recommended that precautions be taken against surge voltage to the equipment the mounts the LEDs.
- Damaged LEDs will show some unusual characteristics such as the leak current remarkably increases, the turn-on voltage becomes lower, or the LEDs do not light at the low current.
- When examining the final product, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. Static-damaged LEDs can easily be found by light-on test or the VF test at a low current.

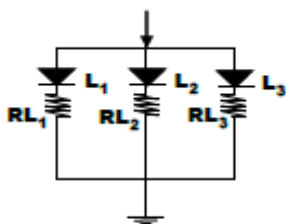
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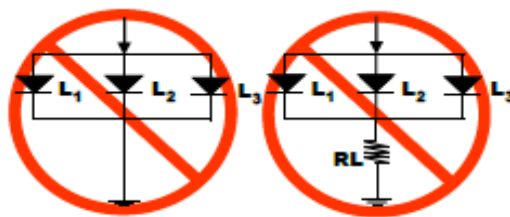
11. Cautions on use (Continued)

11-9. Recommended Circuit

- In designed a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED.
- In general, the LEDs have a variation of forward voltage. Using LEDs with different forward voltages in a circuit with on resistor for the complete circuit causes different forward currents for each LED. This may lead to a variation in brightness. In the worst case, some LED may be subjected to the stresses in excesses of the absolute maximum rating. To avoid brightness variation of LEDs, the use of matrix circuit with one resistor for each LED is recommended.



Pic.1 Recommended Circuit in parallel mode
: Separate resistor must be used in each LED



Pic.2. Abnormal Circuit

The Current through the LEDs may vary due to the variation in forward voltage (V_f) of the LEDs.

- LED should be operated in forward bias. A driving Circuit must be designed so that the LED is not subjected to either forward or reverse voltage while it is off. In particular, if a reverse voltage is continuously applied to the LED, such operation can cause migration resulting in LED damage.
- If reverse voltage is applied to the LEDs, it will damage the Zener diode and LEDs and result in destruction.

11-10. Application limits of LED Driver IC controller

- GaN based LED is relatively weak to electrical damage (such as static electricity and over current stress). Forward leakage of LED occurred by such damage in the forward low current region may result in turn-on-delay of Lighting Module, which is dependent on a specific function of driver IC.
- For reasons mentioned above, minimum current level (source start-up current) of LED driver IC must be more than 0.3 mA. LGIT cannot make a guarantee on the LED using in Driver IC with start up current level of < 0.3 mA.
- When parallel circuit LED driver IC is applied in Lighting Module, Hot spot may occur in low current operation region (dimming mode) by difference of LED voltage in low current region. So, driver IC with Individual LED controller is recommended.

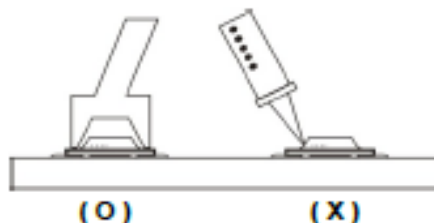
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11. Cautions on use (Continued)

11-11. Repair

- Repairing should not be done after the LEDs have been soldered.
- When repairing is unavoidable, a double-head soldering iron should be used.
- It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- When Soldering, do not put stress on the LEDs during heating customer must finish rework within 5sec. under 245℃.
- The head of Iron can not touch copper foil.
- Twin-head type is preferred.



11-12. Safety Guideline for Human Eyes.

- Users should be cautioned not to stare at the light of this LED product.
- Great care should be taken when viewing directly the LED driven at high current or the LED with optical instruments, which may greatly increase the hazard to your eyes.

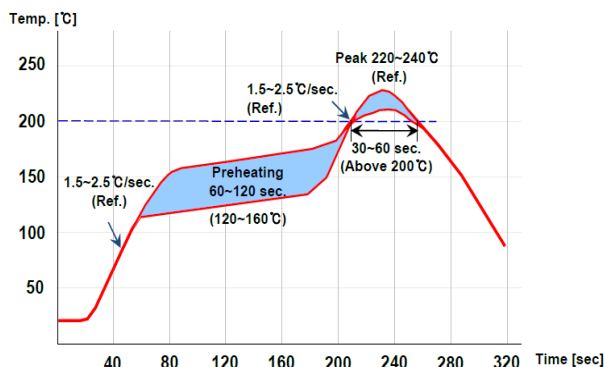
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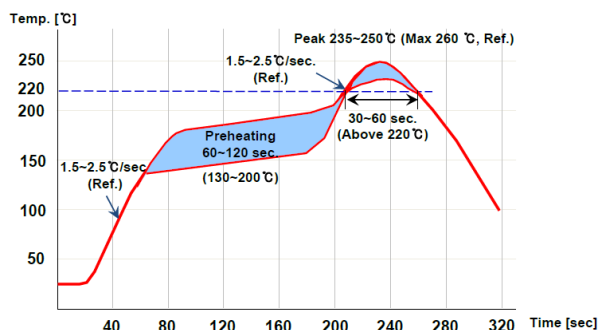
12. Reflow Soldering Characteristics

12-1. Soldering Conditions.

- The LEDs can be soldered in place using the reflow soldering method.
- LG Innotek cannot make a guarantee on the LEDs after they have been assembled using dip soldering method.
- Recommended soldering conditions.
- Pb Solder



- Pb-free Solder



- Although the recommended soldering conditions are specified in the above diagram, reflow or hand soldering at the lowest possible temperature is desirable for the LEDs.
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Occasionally there is a brightness decrease caused by the influence of heat of ambient atmosphere during air reflow. It is recommended that the customer use the nitrogen reflow method.
- The encapsulated material of the LEDs is silicone, Therefore the LEDs have a soft surface on the top of the package. The pressure to the surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So When using the chip mounter, the picking up nozzle that does not affect the silicone resin should be used.
- Reflow soldering should not be done more than two times.

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12. Reflow Soldering Characteristics (Continued)

12-2. Soldering Iron

Basic spec is ≤3sec when 350℃. If temperature is higher, time shorter (+10℃ → -1sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230℃.